*MPEC REPORT 11*

**Connection of the PCB components, Etching of Copper Clad**

WEEKLY PROGRESS:

**Connection of PCB Components:**

In this week, we connected all the components according to the circuit diagram.

Problems faced:

1. We didn’t have the three missing components initially, but we borrowed them from another batch and soldered them accordingly, and connected them as well.

**Etching of Copper Clad:**

In this week, we completed the other half of the process of copper clad etching.

After the ink got transferred, we dipped the copper clad in HCl and H2O2  solution, which removed the excess copper on the surface of the copper clad. After that, we dipped it in water and wiped the ink off. We were then left with copper traces in the shape of our circuit (gerber file).

We then proceeded to drill holes at the spots where we were supposed to attach our components.



